

SPECIFICATION FOR APPROVAL

CUSTOMER : _____

PRODUCT TYPE : SMD GLASS SEALING XTAL 3.2 × 2.5

NOMINAL FREQ. : 20.000000MHz

TXC P/N : 7V20000014

REVISION : S1

CUSTOMER P/N : _____

PM / SALES : _____

DATE : _____

CUSTOMER SIGNATURE & Date _____

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

MSL:Level 1
RoHS Compliant

Pb used in sealing glass material is exempt from EU directive

PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : SMD GLASS SEALING XTAL 3.2 × 2.5

NOMINAL FREQ. : 20.000000MHz

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PE/RD	QA	MFG
 Robin Huang		
12-Sep-12		

NOTE:

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

MSL:Level 1
RoHS Compliant

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<u>Rev</u>	<u>Revise page</u>	<u>Revise contents</u>	<u>Date</u>	<u>Ref.No.</u>	<u>Reviser</u>
S1	N/A	Initial released	12-Sep-12	N/A	Xiaoyan Jiang

Spec Sheet Contents

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■ ELECTRICAL SPECIFICATIONS

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : 25±5℃
Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : 25±3℃
Relative humidity : 40%~70%

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

Crystal cutting type

The crystal is using AT CUT (thickness shear mode).

Unit Weight:

0.018±0.001 g/pcs

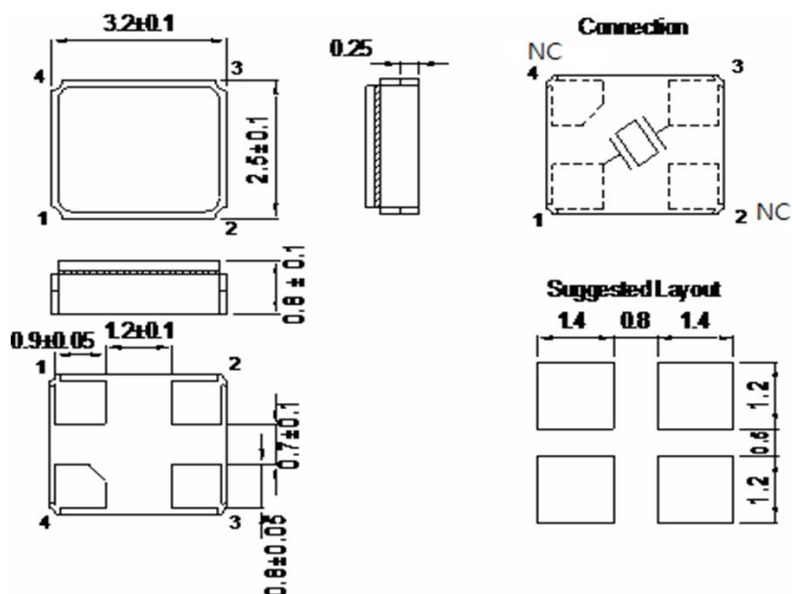
	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYP	MAX	UNITS	
1	Nominal Frequency	FL	20.000000			MHz	-
2	Oscillation Mode	-	Fundamental			-	-
3	Load Capacitance	CL	15			pF	-
4	Frequency Tolerance	-	±10			ppm	at 25 ± 3 °C
5	Frequency Stability	-	±10			ppm	Over Operating Temp. Range (Reference 25℃)
6	Operating Temperature	-	-20	~	70	℃	-
7	Aging	-	±3			ppm	1st Year
8	Drive Level	DL	-	10	100	uW	-
9	Equivalent Resistance R _r	R _r	-	-	60	Ω	-
10	Shunt Capacitance C ₀	C ₀	-	-	5	pF	-
11	Insulation Resistance	-	500	-	-	MΩ	at DC 100V
12	Storage Temperature Range	-	-40	~	125	℃	-

■ FACTORY LOCATION

TXC (NINGBO) CORPORATION
NO.189 Huang Shan West Road, Beilun District,
Ningbo Zhejiang China

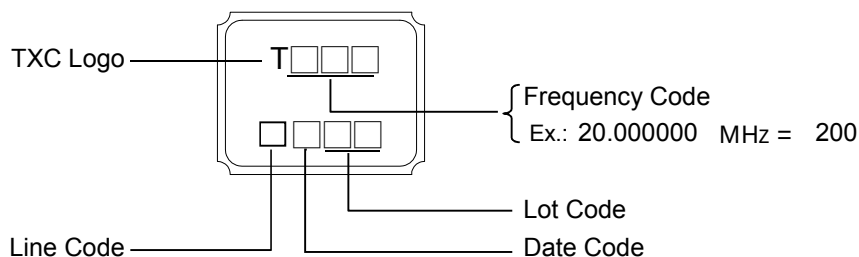
DIMENSIONS

(Unit:mm)



*Coplanarity of solderable areas Camber 0.10 mm Max

MARKING



Date Code:

YEAR				MONTH											
				JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2005	2009	2013	2017	A	B	C	D	E	F	G	H	J	K	L	M
2006	2010	2014	2018	N	P	Q	R	S	T	U	V	W	X	Y	Z
2007	2011	2015	2019	a	b	c	d	e	f	g	h	j	k	l	m
2008	2012	2016	2020	n	p	q	r	s	t	u	v	w	x	y	z

*This date code will be cycled every four years

SUGGESTED REFLOW PROFILE

Solder melting point :220±10 °C, 60 sec. Min.

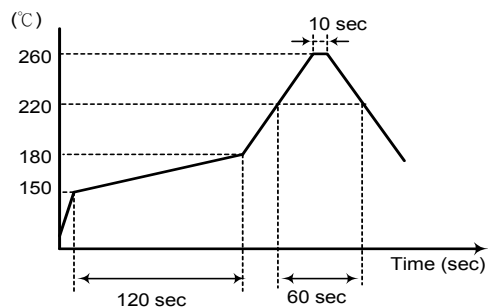
Peak Temperature: 260 ± 5 °C, 10 sec. Max.

SUGGESTED MANUAL SOLDER CONDITION

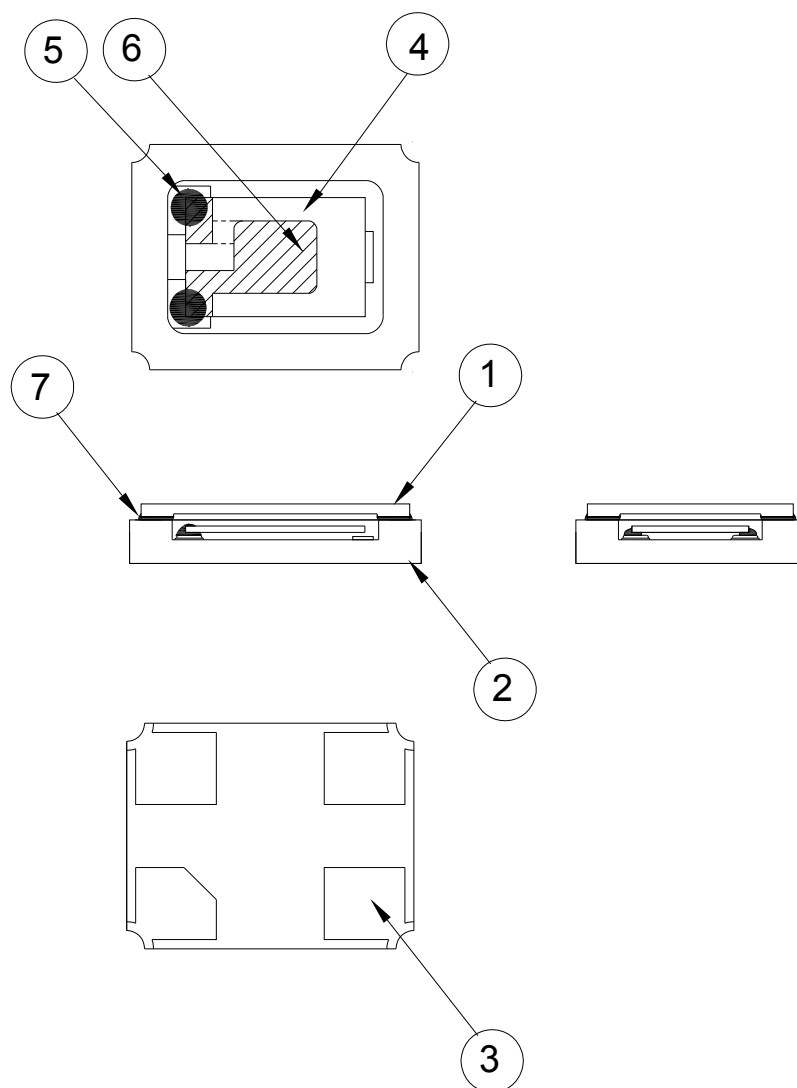
Temperature: 350 ± 10 °C

Time: 3 sec.

Re-solder times: twice

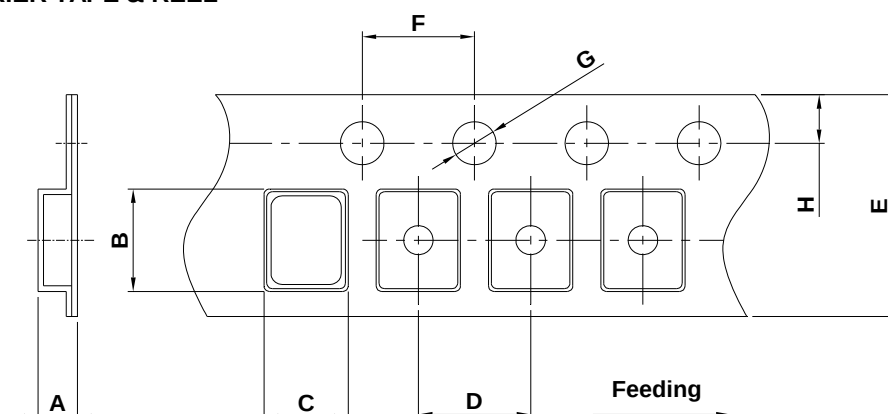


■ STRUCTURE ILLUSTRATION



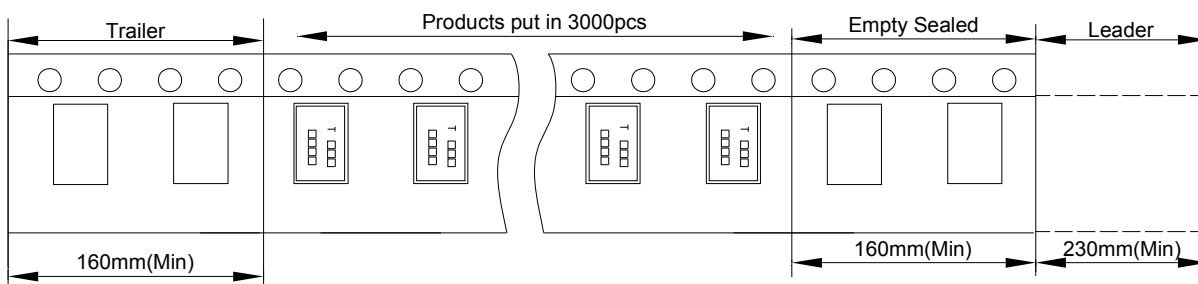
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Cap	Ceramic (Al_2O_3)	-
2	Package	Ceramic (Al_2O_3)	-
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO_2	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Ag	-
7	Sealing Glass	Glass(PbO)	-

EMBOSS CARRIER TAPE & REEL

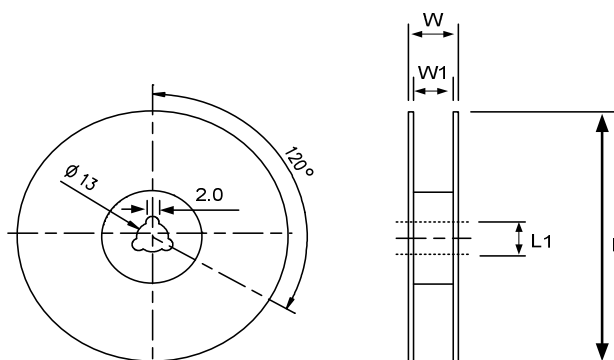


DIMENSIONS	A	B	C	D	E	F	G	H	
	1.65±0.10	3.40±0.10	2.70±0.10	4.00±0.10	8.00±0.20	4.00±0.10	1.55±0.10	1.75±0.10	(UNIT : mm)

REMARK :



User direction of feed



DIMENSIONS	L	L1	W	W1	
	178±1.00	13±0.50	11.5±0.20	8±0.10	(UNIT : mm)

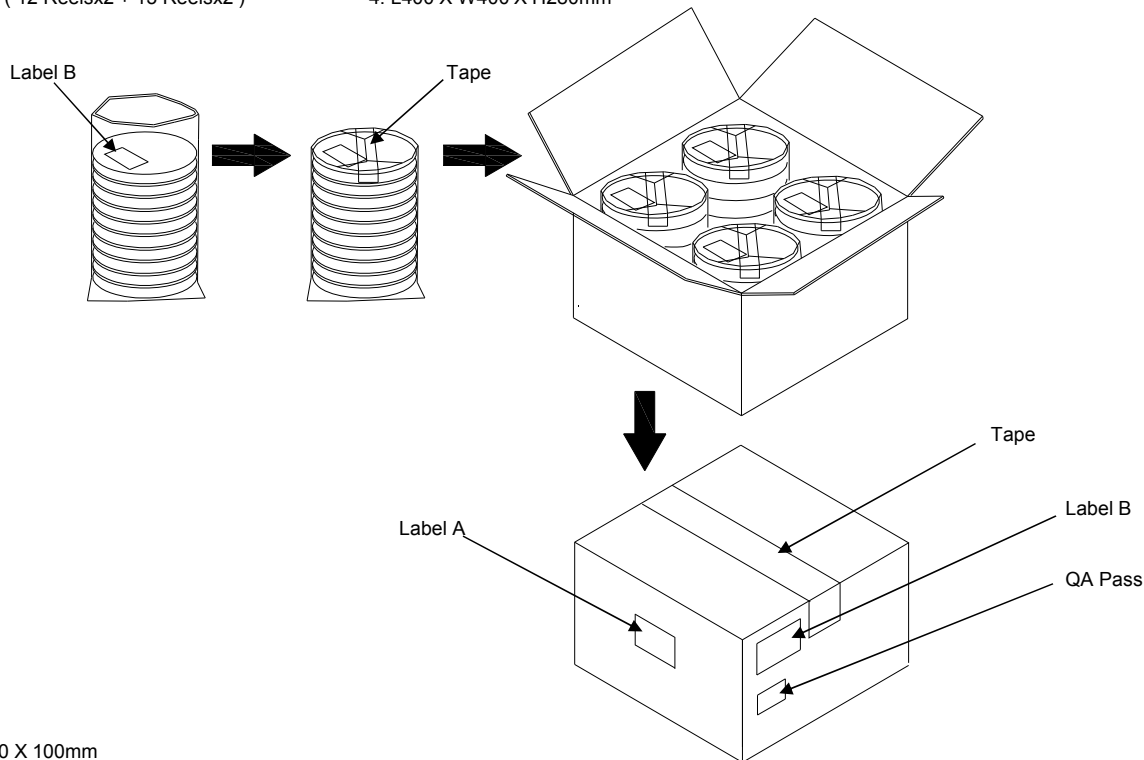
PACKING

Reel Quantity :

1. Reel X 6 (6 Reels)
2. Reel X 12 (12 Reels)
3. Reel X 25 (12 Reels + 13 Reels)
4. Reel X 50 (12 Reelsx2 + 13 Reelsx2)

Box Size:

1. L200 X W200 X H140mm
2. L200 X W200 X H250mm
3. L400 X W200 X H250mm
4. L400 X W400 X H280mm



(Label A) Size:100 X 100mm

TXC	
Inv No: 00096815	
Po No: 21106326- 24- 1	
Part No: 	
Qty: 40000 PCS	
C/No: 157- 44	

(Label B) Size:80 X 40mm

TXC CORPORATION		QA PASS 2011/09/02
DATE CODE: 	QTY: 	
LOT NO: 	RoHS	
PART NO: 	HF	
FREQ: 		

[STORAGE]

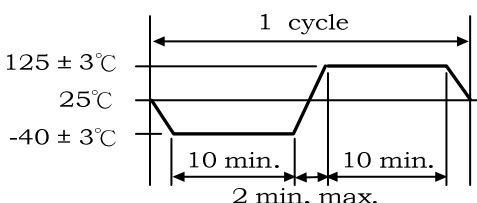
- 1.The storage time to be 1 year maximum.
- 2.Don't be caught in the rain.
- 3.The storage environment shall be 5℃ ~40℃ temperature and 30% ~ 75%RH humidity and free from the sun shine.
- 4.If customers have special requirements, we can paste labels according to it.

■ RELIABILITY SPECIFICATIONS

1.Mechanical Endurance

No.	Test Item	Test Methods	Test Criteria
1.1	Drop Test	150 cm height,3 times on concrete floor .	A . C
1.2	Mechanical Shock	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times. 0.5 ms duration time	A . C
1.3	Vibration	Frequency range 10 ~ 2000 Hz Amplitude 1.52 mm/20G Sweep time 20 minutes Perpendicular axes each test time 4 Hrs (Total test time 12 Hrs)	A . C
1.4	Solderability	Temperature 245 °C ± 5°C Immersing depth 0.5 mm minimum Immersion time 5 ± 1 seconds Flux Rosin resin methyl alcohol solvent (1 : 4)	E

2.Environmental Endurance

No.	Test Item	Test Methods	Test Criteria
2.1	Resistance To Soldering Heat	Pre-heat temperature 125 °C Pre-heat time 60 ~ 120 sec. Test temperature 260 ± 5 °C Test time 10 ± 1 sec.	B . C . D
2.2	High Temp. Storage	+ 125 °C ± 3 °C for 500 ± 12 Hrs	B . C . D
2.3	Low Temp. Storage	- 40 °C ± 3 °C for 500 ± 12 Hrs	B . C . D
2.4	Temperature cycle	Total 100 cycles of the following temperature cycle 	B . C . D
2.5	High Temp & Humidity	85°C ± 3°C , RH 85% , 500 Hrs	B . C . D

■ HANDING CAUTIONS

Prohibit the use of ultrasonic welding in Assembling

RELIABILITY SPECIFICATIONS

Specifications	
A	Frequency change: Within $\pm 5\text{ppm}$ or in customer's specification.
B	Frequency change: Within $\pm 10\text{ppm}$ or in customer's specification.
C	Equivalent series resistance(E.S.R) change: Within $\pm 15\%$ or 10Ω (larger value).
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 2 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.

Measurement condition

Electrical characteristics measured by S&A250B or equivalent.